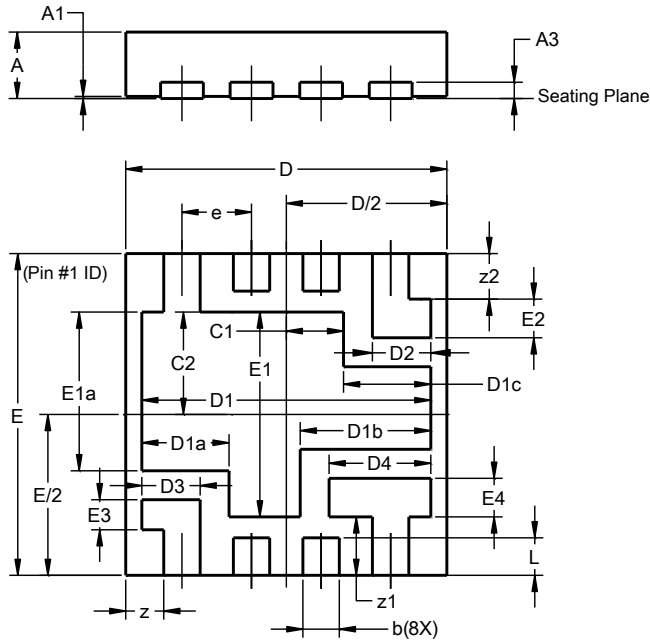


Package Outline Dimensions

U-DFN3030-8 (Type B)

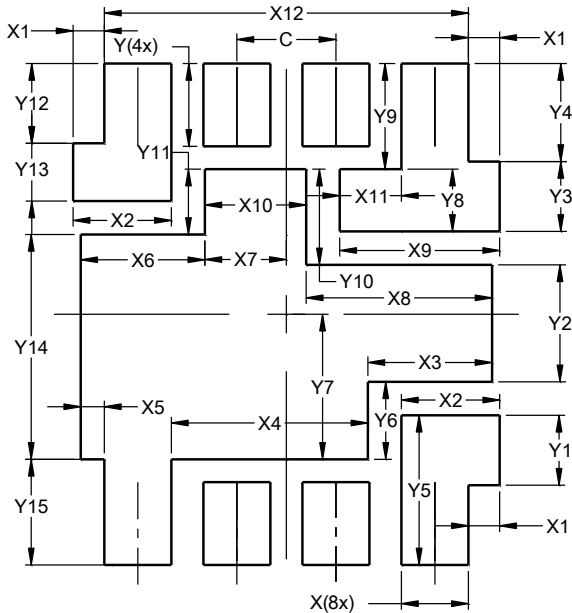


U-DFN3030-8 (Type B)							
Dim	Min	Max	Typ	Dim	Min	Max	Typ
A	0.57	0.63	0.60	E	2.950	3.075	3.000
A1	0	0.05	0.02	E1	1.810	2.010	1.910
A3	-	-	0.15	E1a	-	-	1.480
b	0.29	0.39	0.34	E2	0.260	0.460	0.360
C1	-	-	0.535	E3	0.180	0.380	0.280
C2	-	-	0.955	E4	0.260	0.460	0.360
D	2.950	3.075	3.000	e	-	-	0.65
D1	2.600	2.800	2.700	L	0.30	0.40	0.35
D1a	-	-	0.815	z	-	-	0.355
D1b	-	-	1.220	z1	-	-	0.545
D1c	-	-	0.815	z2	-	-	0.425
D2	0.445	0.645	0.545	-	-	-	-
D3	0.445	0.645	0.545	-	-	-	-
D4	0.850	1.050	0.950	-	-	-	-

All Dimensions in mm

Suggested Pad Layout

U-DFN3030-8 (Type B)



Dimensions	Value (in mm)	Dimensions	Value (in mm)
C	0.650	Y1	0.460
X	0.440	Y2	0.770
X1	0.205	Y3	0.460
X2	0.645	Y4	0.645
X3	0.815	Y5	0.985
X4	1.290	Y6	0.510
X5	0.155	Y7	0.955
X6	0.815	Y8	0.410
X7	0.535	Y9	0.695
X8	1.220	Y10	0.630
X9	1.050	Y11	0.430
X10	0.665	Y12	0.525
X11	0.405	Y13	0.380
X12	2.390	Y14	1.480
Y	0.545	Y15	0.695

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.